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(54) **WAFER SINGULATING METHOD AND LED CHIP AND LIGHT EMITTING MODULE**

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(57) **ABSTRACT**

A wafer singulating method includes: providing a wafer product having front and back sides the front side being formed with scribe lines; deep scribing with a laser along the scribe lines on the front side to form a plurality of intersecting trenches; and cleaving the back side along the trenches on the front side. The cleaving of the back side proceeds in different directions each of which is directed to a center of the wafer product from a periphery of the wafer product. The cleaving in each of the directions proceeds along the trenches one after the other from one of the trenches nearest to the periphery of the wafer product and ceases near or at the center.

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